Trevor Braun

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/7075353/publications.pdf

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21	262	9	16
papers	citations	h-index	g-index

1040056

940533

21	21	21	224
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Simulating the Influence of Supporting Electrolyte Concentration on Copper Electrodeposition in Microvias. Journal of the Electrochemical Society, 2022, 169, 012502.	2.9	12
2	Microstructure and Texture in Copper Filled Millimeter Scale Through Silicon Vias. Journal of the Electrochemical Society, 2022, 169, 032508.	2.9	2
3	Mapping Surface Chemistry During Superfilling with Shell-Isolated Nanoparticle Enhanced Raman Spectroscopy and X-ray Photoelectron Spectroscopy. Journal of the Electrochemical Society, 2022, 169, 082506.	2.9	6
4	Simulating Cu electrodeposition in high aspect ratio features: Effect of control mode and uncompensated resistance in S-NDR systems. Electrochimica Acta, 2021, 375, 137925.	5.2	8
5	Effect of Chloride on Microstructure in Cu Filled Microscale Through Silicon Vias. Journal of the Electrochemical Society, 2021, 168, 112501.	2.9	6
6	High-Aspect-Ratio Ag Nanowire Mat Electrodes for Electrochemical CO Production from CO₂. ACS Catalysis, 2021, 11, 11945-11959.	11.2	20
7	Editors' Choiceâ€”Simulation of Copper Electrodeposition in Through-Hole Vias. Journal of the Electrochemical Society, 2020, 167, 013510.	2.9	23
8	Microelectrode Studies of S-NDR Copper Electrodeposition: Potentiodynamic and Galvanodynamic Measurements and Simulations. Journal of the Electrochemical Society, 2020, 167, 082509.	2.9	10
9	A High-Throughput Structural and Electrochemical Study of Metallic Glass Formation in Niâ€“Tiâ€“Al. ACS Combinatorial Science, 2020, 22, 330-338.	3.8	31
10	Simulation of Copper Electrodeposition in Millimeter Size Through-Silicon Vias. Journal of the Electrochemical Society, 2020, 167, 162508.	2.9	5
11	Simulation of Copper Electrodeposition in Through-Hole Vias. Journal of the Electrochemical Society, 2020, 167, .	2.9	0
12	Exploring the Kinetic and Thermodynamic Relationship of Charge Transfer Reactions Used in Localized Electrodeposition and Patterning in a Scanning Bipolar Cell. Frontiers in Chemistry, 2019, 7, 340.	3.6	3
13	Effect of Chloride Concentration on Copper Deposition in Through Silicon Vias. Journal of the Electrochemical Society, 2019, 166, D3259-D3271.	2.9	32
14	Effect of Chloride Concentration on Copper Deposition in Through Silicon Vias. Journal of the Electrochemical Society, 2019, 166, .	2.9	1
15	Superconformal Nickel Deposition in Through Silicon Vias: Experiment and Prediction. Journal of the Electrochemical Society, 2018, 165, D291-D300.	2.9	22
16	Superconformal Nickel Deposition in Through Silicon Vias: Experiment and Prediction. Journal of the Electrochemical Society, 2018, 165, .	2.9	0
17	Bipolar Electrochemical Displacement: A New Phenomenon with Implications for Selfâ€Limiting Materials Patterning. ChemElectroChem, 2016, 3, 441-449.	3.4	10
18	Remote Control Electrodeposition: Principles for Bipolar Patterning of Substrates without an Electrical Connection. Journal of the Electrochemical Society, 2016, 163, D3014-D3019.	2.9	3

#	Article	IF	Citations
19	Analytical and Computational Scaling Relationships for the Coupled Phenomena that Control Local Bipolar Electrochemical Behavior. Journal of the Electrochemical Society, 2016, 163, E354-E362.	2.9	3
20	The Emerging Role of Electrodeposition in Additive Manufacturing. Electrochemical Society Interface, 2016, 25, 69-73.	0.4	34
21	Localized Electrodeposition and Patterning Using Bipolar Electrochemistry. Journal of the Electrochemical Society, 2015, 162, D180-D185.	2.9	31